

# M62001L/FP to M62008L/FP

# Low Power 2 Output System Reset IC Series

REJ03D0781-0100 Rev.1.00 Sep 14, 2005

## **Description**

The M62001 to M62008 are semiconductor integrated circuits whose optimum use is for the detection of the rise and fall in the power supply to a microcomputer system in order to reset or release the microcomputer system.

The M62001 to M62008 carry out voltage detection in two-steps and have two output pins. As Bi-CMOS process and low power dissipating circuits are employed, they output optimum signals through each output pin to a system that requires RAM backup. As output signals, interruption  $(\overline{INT})$  and compulsive reset  $(\overline{RESET})$  signals are available. The interruption signal  $(\overline{INT})$  is used to alter the microcomputer from normal mode to backup mode and vice versa. These output signals are classified into pulse type (M62001 to M62004) and hold type (M62005 to M62008).

### **Features**

• Bi-CMOS process realizes a configuration of low current dissipating circuits.

Circuit current

 $I_{CC} = 5~\mu A$  (Typ, normal mode,  $V_{CC} = 5.0~V)$ 

 $I_{CC} = 1 \mu A$  (Typ, backup mode,  $V_{CC} = 2.5 \text{ V}$ )

• Two-step detection of supply voltage

Detection voltage in normal mode (2 types)

 $V_S = 4.45 \text{ V}/4.25 \text{ V (Typ)}$ 

Detection voltage in backup mode

$$V_{BATT} = 2.15 \text{ V (Typ)}$$

Two outputs

Reset output (RESET): output of compulsive reset signal Interruption output (INT): output of interruption signal

- Two types of output forms: CMOS and open drain
- Two types of interruption output (INT) signals

Pulse type (M62001 to M62004)

Hold type (M62005 to M62008)

• Two types of outline packages

5-pin plastic SIP (single in-line package)

8-pin plastic SOP (mini flat package)

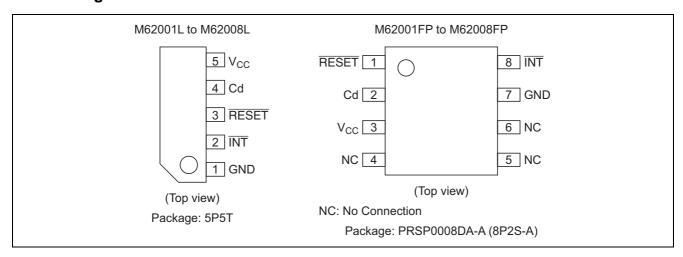
• Output based on RAM backup mode (see the timing chart)

## **Application**

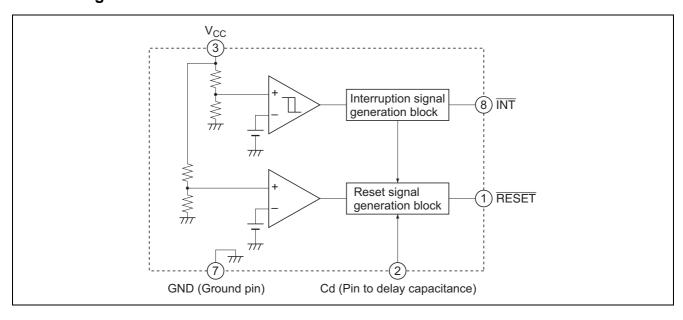
 Prevention of errors in microcomputer system in electronic equipment that requires RAM backup, such as office, industrial, and home-use equipment.



# **Pin Arrangement**



# **Block Diagram**



# **Absolute Maximum Ratings**

(Ta = 25°C, unless otherwise noted)

Item	Symbol	Ratings	Unit	Conditions
Supply voltage	V <sub>CC</sub>	8	V	
Output sink current	Isink	5	mA	
Power dissipation	Pd	440	mW	
Thermal derating	Кθ	4.4	mW/°C	Ta ≥ 25°C
Operating temperature	Topr	-20 to +75	°C	
Storage temperature	Tstg	-40 to +125	°C	

## **Electrical Characteristics**

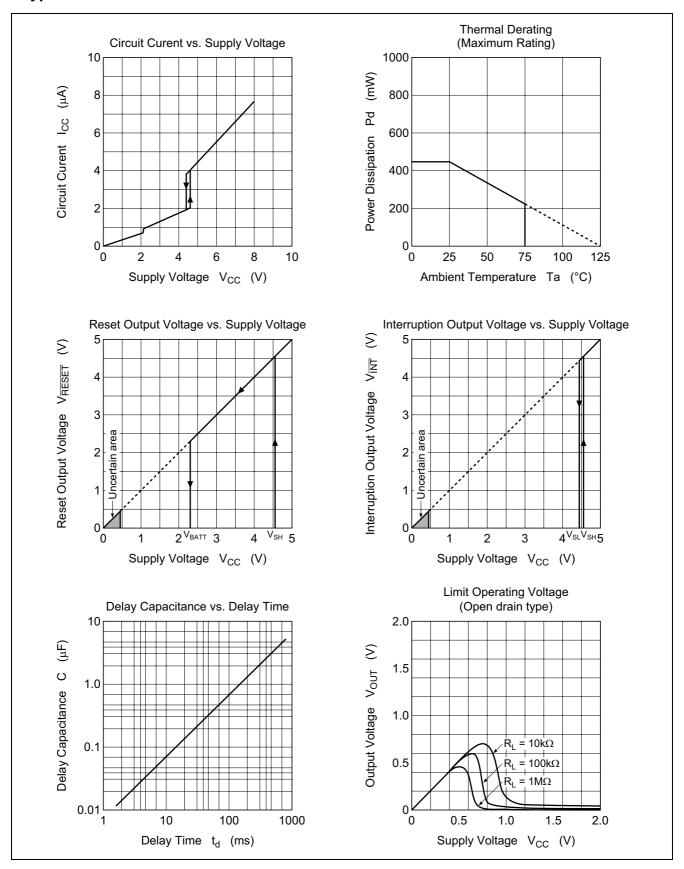
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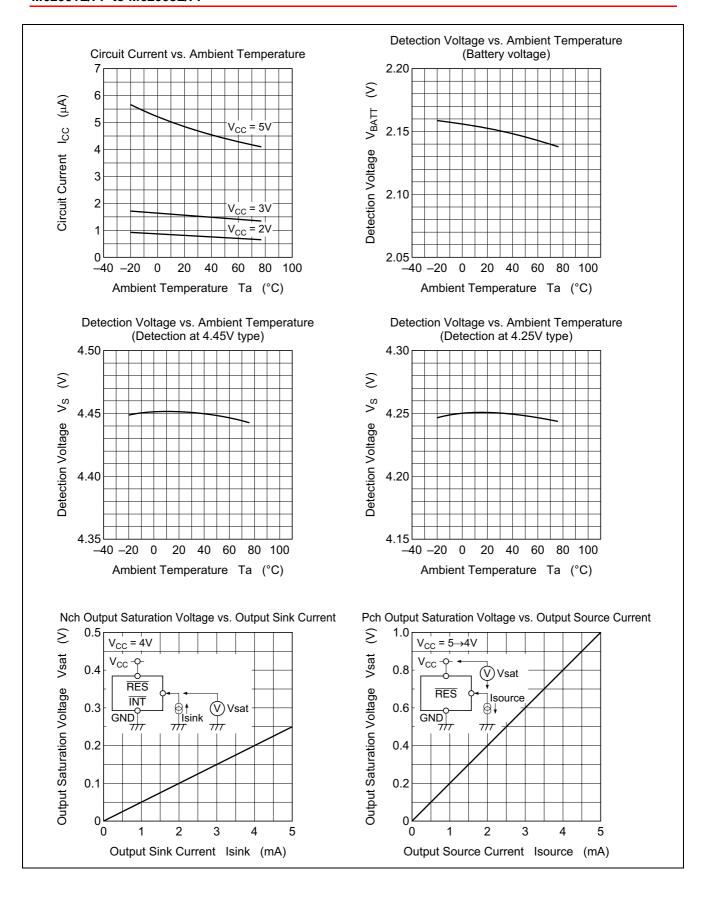
Item	Symbol	Min	Тур	Max	Unit	Test Conditions	
Supply voltage	Vs	4.30	4.45	4.60	V	Interruption level during V <sub>CC</sub> drop	M62001, M62002,
						(Equivalent to $V_{SL}$ )	M62005, M62006,
		4.05	4.25	4.45			M62003, M62004,
							M62007, M62008,
Battery voltage	$V_{BATT}$	2.00	2.15	2.30		Reset level at backup	
Hysteresis voltage	$\Delta V_S$		100		mV	$\Delta V_S = V_{SH} - V_{SL}$	
Circuit current	Icc	_	5.0	20	μА	V <sub>CC</sub> = 5.0V: in normal mode	
		_	1.0	4		V <sub>CC</sub> = 2.5V: in backup mode	
Sink ability	Vsat1	_	0.2	0.4	V	$V_{CC} = 4V$ , $I_O = 4mA$	
						(Output saturation voltage of N-ch transistor)	
Source ability	Vsat2	_	0.2	0.4		$V_{CC} = 4V$ , $I_{O} = 1mA$	
						(Output saturation voltage of P-ch transistor)	
						[CMOS output] M62001, M62003, M6	62005, M62007
Delay time	t <sub>d</sub>	_	50		ms	External capacitance Cd = 0.33μF	
Pulse width	t <sub>pw</sub>	_	7	10	μS	Output pulse width (M62001, M62002, M62003, M62004)	
Reset output	t <sub>RESET</sub>	_	30	_	μS	Time between V <sub>CC</sub> (when falling) = V <sub>BATT</sub> and output of	
response time						RESET signal	
Interruption output	t <sub>INT</sub>	_	100		μS	Time between $V_{CC}$ (when falling) = $V_S$ and output of $\overline{INT}$	
reset time						signal	

# Summary of M62001L/FP to M62008L/FP

	Supply Voltage Detection	Battery Voltage Detection		Interruption Signal
Type No.	Level V <sub>S</sub> (V)	Level V <sub>BATT</sub> (V)	Output Form	Output Mode
M62001L/FP	4.45	2.15	CMOS	Pulse output
M62002L/FP			Open drain	
M62003L/FP	4.25		CMOS	
M62004L/FP			Open drain	
M62005L/FP	4.45		CMOS	Hold output
M62006L/FP			Open drain	
M62007L/FP	4.25		CMOS	
M62008L/FP			Open drain	

# **Typical Characteristics**





## **Operating Principle**

### Description

In general, the memory backup function of a microcomputer, as shown in figure 1, uses two diodes to switch between main power supply and backup power supply. The M62001 to M62008 are ICs that, in such memory backup operation, monitor in two steps each voltage on the  $V_{DD}$  line.

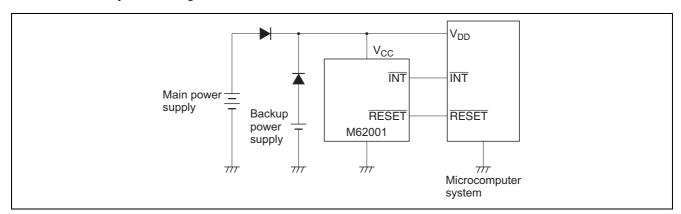


Figure 1

The ICs have an intelligent sequence such as substantial hysteresis action of RESET toward normal state at restoration of supply voltage, as well as two-step detection in low power dissipation mode.

### **Detailed Description**

1. Two-step detection

The ICs perform two-step detection of supply voltage and have two output pins ( $\overline{\text{INT}}$  and  $\overline{\text{RESET}}$ ). Although they have two comparators for two-step detection, they differ significantly from such that are simply provided with independent detectors, because the  $\overline{\text{RESET}}$  output signal is dependent at power-up and the like upon the  $\overline{\text{INT}}$  output signal.

2. INT output (Detection of 4.45 V and 4.25 V)

The  $\overline{INT}$  output at the power-up of supply voltage detects  $V_{SH}$  (4.45 V/4.25 V) to inform the microcomputer system of the fact that the supply voltage has reached its normal level. When the supply voltage drops from its normal level to  $V_{SL}$  (4.45 V/4.25 V) an interruption signal is output to alter the microcomputer system into RAM backup mode. The microcomputer at this point enters sleep state and secures memory by a stop command issued by the interruption signal. These detection voltage,  $V_{SH}$  the rise, and  $V_{SL}$  the fall, of supply voltage, have a 100 mV hysteresis voltage between themselves.

$$V_{SH} - V_{SL} \approx 100 \; (mV)$$

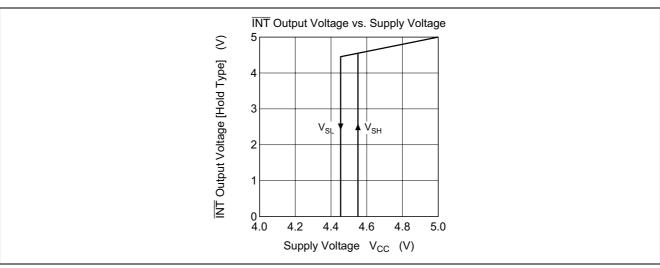


Figure 2 INT Output (Detection of 4.45 V and 4.25 V)

### 3. RESET output (Detection of 2.15 V)

The  $\overline{RESET}$  outputs a signal to prevent the microcomputer from malfunctioning due to a drop in supply voltage. When powering up,  $\overline{RESET}$  is kept at low level until the supply voltage reaches  $V_{SH}$ . If the supply voltage rises to  $V_{SH}$ ,  $\overline{RESET}$  is set to high level. By inserting a capacitor between the Cd pin and GND, it is possible to produce a desired delay time ( $t_d$ ). To set a delay time, equation below is used.

$$t_d \approx 1.52 \times 10^5 \times C \text{ (s)}$$

Once the supply voltage has exceeded  $V_{SH}$  and the  $\overline{RESET}$  output is set to high level,  $\overline{RESET}$  maintains the high level until the supply voltage drops to  $V_{BATT}$ . When the supply voltage drops to  $V_{BATT}$ ,  $\overline{RESET}$  goes low thereby resetting and initializing the microcomputer.

The  $\overline{RESET}$  output has a large hysteresis voltage of approximately 2 V between the rise in supply voltage at power-up and its fall.

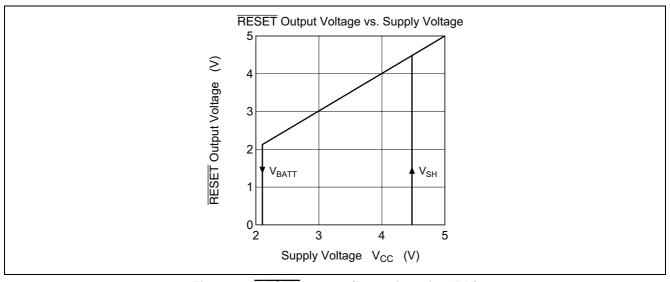


Figure 3 RESET Output (Detection of 2.15 V)

## **Operating Description**

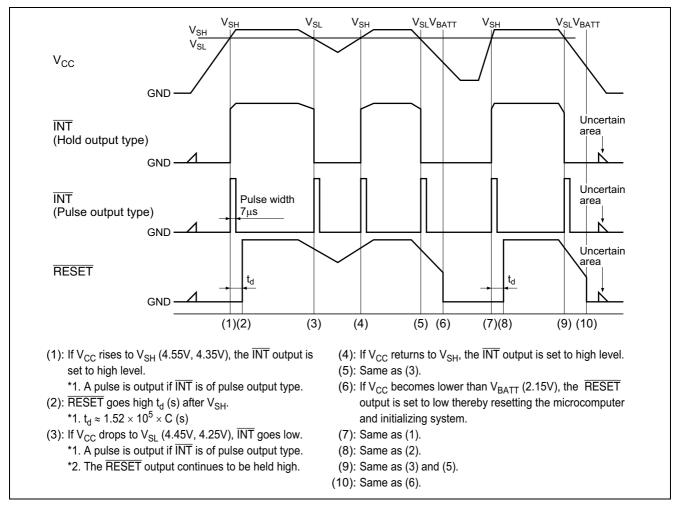


Figure 4 Operating Waveform

# **Application Example**

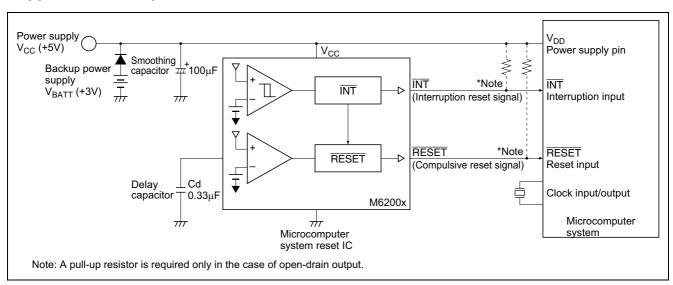
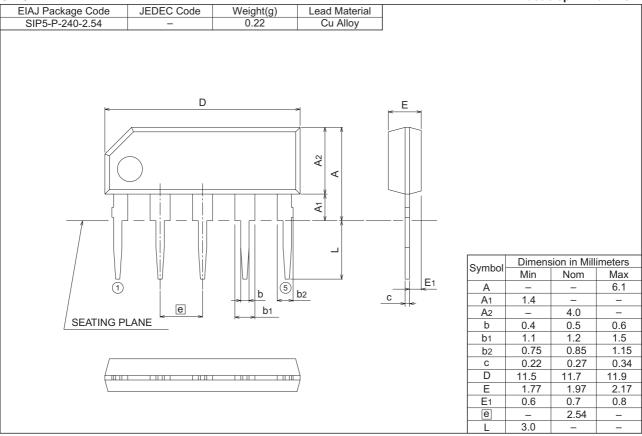
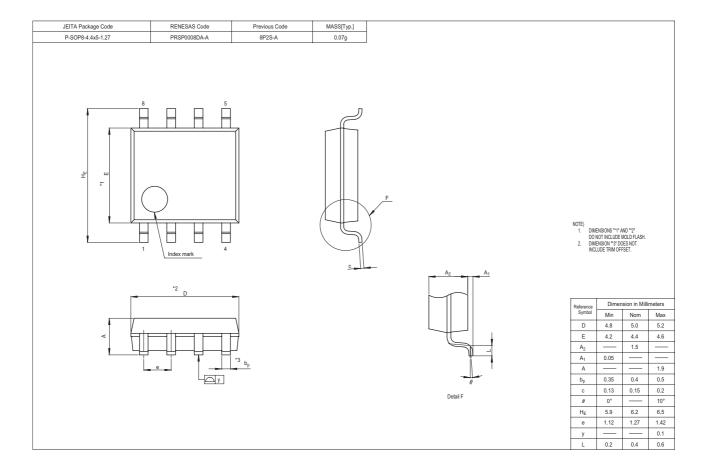


Figure 5 Application Example

# **Package Dimensions**

5P5T Plastic 5pin 240mil SIP





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